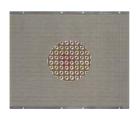
Vectorbord® Circbordtm

Vectorbord® Circbordtm offers an assortment of basic printed circuit pattern prototyping boards for solder or wire-wrap connections. A wide selection of tin or gold plated terminals and wire-wrap pins located on pages 70-72.

Round Pads-Per-Hole with .025" Holes, .050" Grid

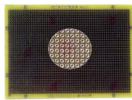
8015 4.0"Hx6.0"L x .062" TH

Round Pads-Per-Hole with 0.042" Holes, .100" Grid



8021 3.94"Hx6.3"Lx .062" TH (100MM x 160MM) 3U Eurocard size

0.050" grid "M" pattern, 0.024" diameter holes with 0.034" diameter pads, both sides. Copper plated-thru- holes, solder coated pattern. Material: FR4 Inbord Pin: K36C



0.100" grid Pad-Per-Hole Pattern. .042" holes plated thru with .080" isolated solder pad around each hole on both sides. 16-Pin DIP= 72.

Material: FR4.

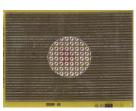
WW Terminals: T44, T46, T49, T68. Solder Terminals: T42-1, K24C WW Socket Pin: R32

Strip Busses with 0.042" Holes, .100" Grid

8022 3.0"Hx3.5"L x .062" TH

0.100" grid, economical size, 32 stripline tracks (in 3.0" direction), 29 holes per track. For common bus or signal lines or break pad at any desired number of holes. Copper plated-thruholes, solder coated pattern. Material: FR4

WW Terminals: T44, T46, T49, T68 Solder Terminals: T42-1 WW Socket Pin: R32



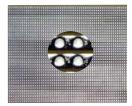
8010 4.0"Hx12.860"L x .062" TH

0.100" grid Pad-Per-Hole Pattern on both sides. Board approximates MACII specification.

.042" holes plated thru with .080" isolated solder pad around each hole on both

16-Pin DIP= 124. Material: FR4. WW Terminals: T44, T46, T49, T68. Solder Terminals: T42-1

WW Socket Pin: R32



8019 3.94"H x 6.3"L x .062" TH

3U Eurocard size

0.100" grid, economical size, 38 lengthwise stripline tracks (in 6.3" direction), 64 holes per track. For common bus or signal lines, or break pad at any desired number of holes. Copper plated-thru-holes, solder coated pattern. Material: FR4

WW Terminals: T44, T46, T49, T68 Solder Terminals: T42-1 WW Socket Pin: R32

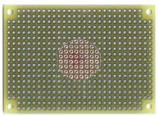


8002 4.5"Hx6.5"L x .062" TH

0.100" grid Interleave Bus Pattern on one side only, no plating or etch on reverse side. Components can be mounted on 0.3", 0.6" and 0.9" lead spacing. 0.042" holes with Power/GND busses. I/O area with square pads for connector mounting. Solder coated pattern. Material: CEM-1

WW Terminals: T44, T46, T49, T68. Solder Terminals: T42-1 WW Socket Pin: R32

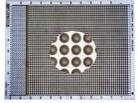




8029 2.0"Hx3.0"L x .062" TH

0.100" grid, Pad-Per-Hole Pattern on both sides, 0.042" holes plated-thru copper. Small economical size ideal for mounting on standoffs. Solder coated pattern. 16-Pin DIP capacity = 24 Material: FR4

WW Terminals: T44, T46, T49, T68 Solder Terminals: T42-1 WW Socket Pin: R32



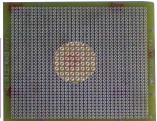
8004 4.50"Hx6.50"Lx.062"TH

0.100" grid single sided w/overall Ground Plane only Single-sided with no etch & plating on reverse side 042" holes with 080" clearance around

each hole. I/O area w/square solder pads for mounting connector 16-Pin DIP = 50

Material: FR-4

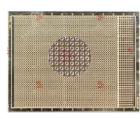
WW Terminals: T44,T 46, T49, T68 Solder Terminals: T42-1 WW Socket Pin: R32



8015-1 4.0"Hx4.0"L x .062" TH

0.100" grid Pad-Per-Hole 1 sided Pattern No etch or plating on reverse side .042" holes with isolated round pad around each hole 16-Pin DIP= 72

Material: FR4 WW Terminals: T44, T46, T49, T68 Solder Terminals: T42-1, K24C WW Socket Pin: R32



8007 4.50"Hx6.50"L x .062" TH

0.100" grid Pad-Per-Hole Pattern on component side - overall Ground Plane pattern on wiring side .042" holes not plated thru with .080" isolated solder pad I/O area w/square solder pads for mounting connector

16-Pin DIP= 60 Material: CEM-1

WW Terminals: T44, T46, T49, T68 Solder Terminals: T42-1

WW Socket Pin: R32

